

MSCDC200H170AG
Datasheet
SiC Diode Full Bridge Power Module

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a  **MICROCHIP** company

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1 Revision History

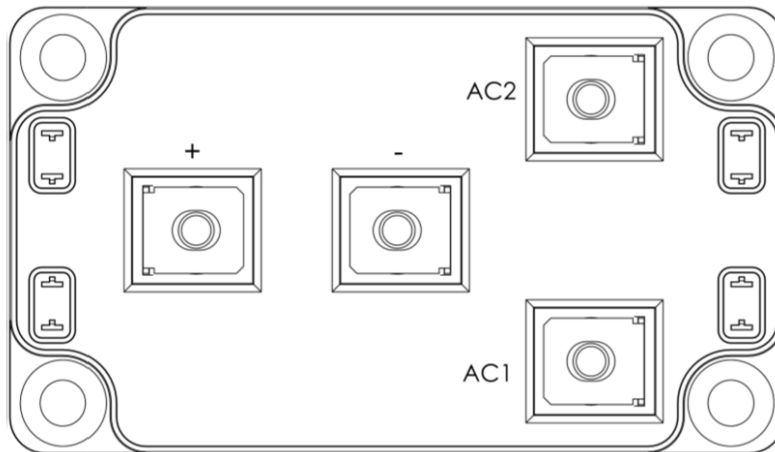
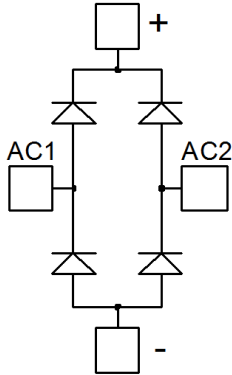
The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

1.1 Revision 1.0

Revision 1.0 was published in December 2019. It is the first publication of this document.

2 Product Overview

This section provides the product overview for the MSCDC200H170AG device.



All ratings at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified.

Caution: These devices are sensitive to electrostatic discharge. Proper handling procedures should be followed.

2.1 Features

The following are key features of the MSCDC200H170AG device:

- Silicon Carbide (SiC) Schottky diode
 - Zero reverse recovery
 - Zero forward recovery
 - Temperature independent switching behavior
 - Positive temperature coefficient on VF
- High blocking voltage
- Low stray inductance
- M5 power connectors
- Aluminum nitride (AlN) substrate for improved thermal performance

2.2 Benefits

The following are benefits of the MSCDC200H170AG device:

- Outstanding performance at high frequency operation
- Low losses
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant

2.3 Applications

The MSCDC200H170AG device is designed for the following applications:

- Uninterruptible power supply (UPS)
- Induction heating
- Welding equipment
- High-speed rectifiers

3 Electrical Specifications

This section provides the electrical specifications for the MSCDC200H170AG device.

3.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings per diode for the MSCDC200H170AG device.

Table 1 • Absolute Maximum Ratings

Symbol	Parameter	Max Ratings	Unit
V_{RRM}	Repetitive peak reverse voltage	1700	V
I_F	DC forward current	$T_C = 125\text{ }^\circ\text{C}$ 200	A

The following table shows the thermal and package characteristics of the MSCDC200H170AG.

Table 2 • Thermal and Package Characteristics

Symbol	Characteristic	Min	Max	Unit		
V_{ISOL}	RMS isolation voltage, any terminal to case $t = 1$ minute, 50 Hz/60 Hz	4000		V		
T_J	Operating junction temperature range	-40	175	$^\circ\text{C}$		
T_{JOP}	Recommended junction temperature under switching conditions	-40	$T_{Jmax} - 25$			
T_{STG}	Storage temperature range	-40	125			
T_C	Operating case temperature	-40	125			
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package weight			300	g	

3.2 Electrical Performance

The following table shows the electrical characteristics per diode of the MSCDC200H170AG.

Table 3 • Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
V_F	Diode forward voltage	$I_F = 200\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$		1.5	1.8	V
			$T_J = 175\text{ }^\circ\text{C}$		2		
I_{RM}	Reverse leakage current	$V_R = 1700\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$		200	800	μA
			$T_J = 175\text{ }^\circ\text{C}$		1000		

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
Q_C	Total capacitive charge	$V_R = 900\text{ V}$		1640		nC
C	Total capacitance	$f = 1\text{ MHz}, V_R = 600\text{ V}$		1200		pF
		$f = 1\text{ MHz}, V_R = 900\text{ V}$		1000		
R_{thJC}	Junction-to-case thermal resistance				0.092	$^{\circ}\text{C/W}$

3.3 Typical Performance Curves

This section shows the typical performance curves for the MSCDC200H170AG device.

Figure 1 • Maximum Transient Thermal Impedance

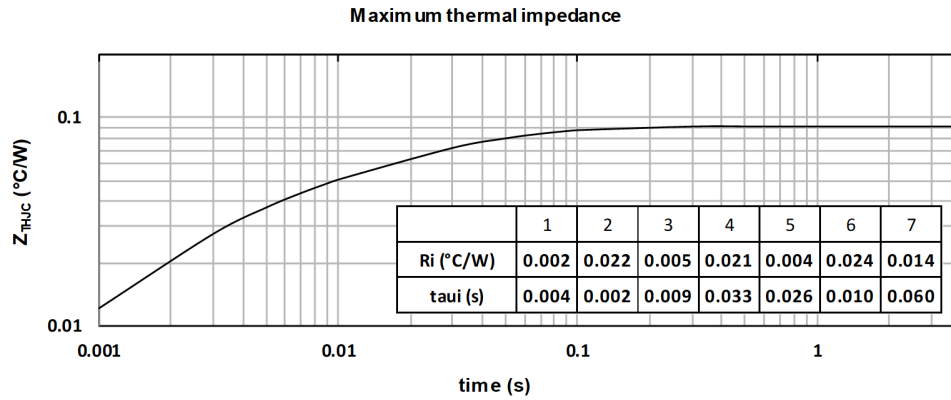


Figure 2 • Forward Current vs. Forward Voltage

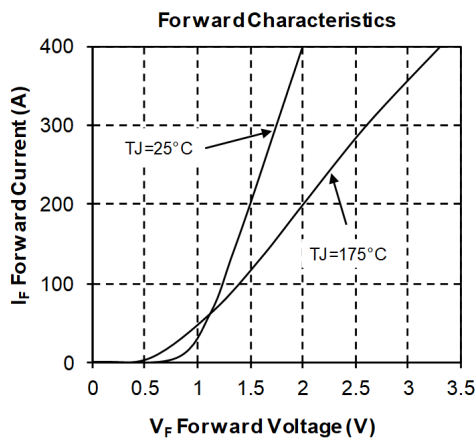
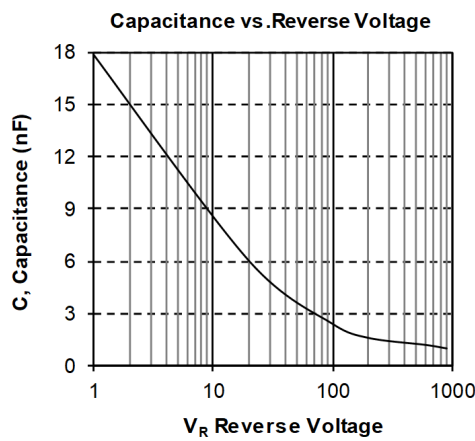


Figure 3 • Capacitance vs. Reverse Voltage



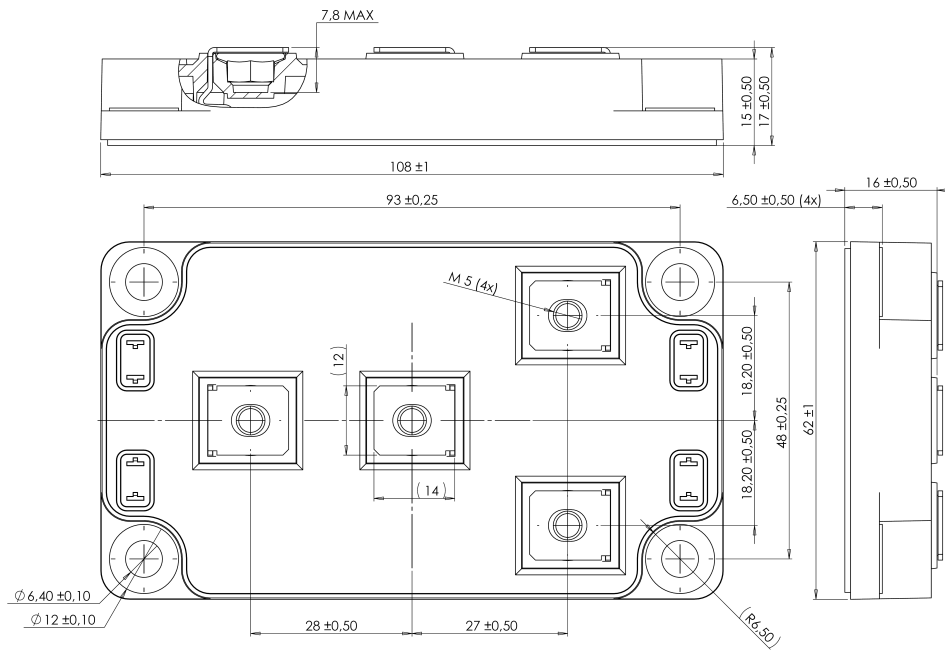
4 Package Specifications

This section shows the package specifications for the MSCDC200H170AG device.

4.1 Package Outline Drawing

The following image illustrates the package outline of the MSCDC200H170AG device. The dimensions in the following figure are in millimeters.

Figure 4 • Package Outline Drawing





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